

11/28/02

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Washington, D.C. 20231

Doc No. **TS01-1063**

59/82/10
10/058473
JCSST U.S. PTO

Transmitted herewith for filing is the Patent Application of:

Inventor: **KEN CHEN, CHENDER HUANG, PEI-HAW TSAO, JONES WANG, HANK HUANG**

For: **ENHANCED ADHESION STRENGTH BETWEEN MOLD RESIN AND POLYIMIDE**

Enclosed are:

- ☒ 3 sheets of drawing(s) - formal.
☐ An assignment of the invention to
☐ An associate power of attorney ☐ Applicant claims small entity status
☒ Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 740.
TOTAL CLAIMS	31 -20=	11	x 18 =	\$ 198.
INDEP CLAIMS	10 -3=	7	x 84 =	\$ 588.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
SUB TOTAL				\$ 1526.
ASSIGNMENT				\$.
TOTAL				\$ 1526.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,526. A duplicate copy of this sheet is enclosed.
☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
☒ Any additional filing fees required under 37 CFR \$1.16.
☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,
STEPHEN B. ACKERMAN, REG. NO. 37,761

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Washington, D.C. 20231. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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**NONPUBLICATION REQUEST
UNDER
35 U.S.C. 122(b)(2)(B)(i)**

First Named Inventor

Ken Chen

Title

*Enhanced Adhesion Strength
Between Mold Resin and Polyimide*

Atty Docket Number

TS01-1063

I hereby certify that the invention disclosed in the attached application **has not and will not** be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

1/28/02

Date

[Signature]

Signature

Stephen B. Ackerman, Reg #37761

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**